



Material Content Data Sheet



Sales Product Name		BTS5045-1EJA		Issued		24. January 2018			
MA#		MA001346588							
Package		PG-DSO-8-43		Weight*		84.30 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.775	2.11	2.11	21058	21058	
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		111		
	non noble metal	zinc	7440-66-6	0.038	0.04		446		
	non noble metal	iron	7439-89-6	0.752	0.89		8919		
wire	non noble metal	copper	7440-50-8	30.529	36.21	37.15	362139	371615	
	non noble metal	copper	7440-50-8	0.361	0.43	0.43	4278	4278	
	encapsulation	organic material	carbon black	1333-86-4	0.097	0.12		1154	
plastics	plastics	epoxy resin	-	4.476	5.31		53090		
	inorganic material	silicondioxide	60676-86-0	44.074	52.27	57.70	522818	577062	
leadfinish	non noble metal	tin	7440-31-5	0.814	0.97	0.97	9654	9654	
plating	noble metal	silver	7440-22-4	0.726	0.86	0.86	8612	8612	
glue	plastics	epoxy resin	-	0.114	0.14		1351		
	noble metal	silver	7440-22-4	0.537	0.64	0.78	6370	7721	
*deviation	< 10%				Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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